

Industrial SD Card

3ME3

Customer: _____

Customer

Part

Number: _____

Innodisk

Part

Number: _____

Innodisk

Model Name: _____

Date: _____

Innodisk Approver	Customer Approver

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REVISION HISTORY

Revision	Description	Date
Preliminary	First release	June, 2017
1.0	Officially release	August, 2017
1.1	Add Power cycling function	March, 2018
1.2	Add P/E cycle	May, 2020

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1. Product Overview

1.1 Introduction of Innodisk Industrial SD 3ME3

Innodisk 3ME3 is an industrial-grade SD card solution with an integrated industrial controller, which is designed for embedded applications. With enhanced flash technologies and a powerful configurable BCH ECC engine, SD 3ME3 can achieve high-speed data transfer rates.

Innodisk industrial SD 3ME3 provides a wide range of capacities from 8GB to 128GB with MLC NAND Flash, and is fully compliant with SD3.0 and SD2.0 specifications.

Innodisk industrial SD 3ME3 are specifically designed for industrial PC and embedded applications for high performance. With its low power consumption and the above mentioned features, Innodisk industrial SD 3ME3 can be applied for industrial automation, SBC (single-board computer), medical equipment, infotainment, and mobile applications.

1.2 Product View and Models

Innodisk Industrial SD 3ME3 is available from 8GB up to 128GB capacities within MLC Flash IC.



Figure 1: Innodisk Industrial SD 3ME3

1.3 SD 3.0 Interface

Innodisk Industrial SD 3ME3 support SD 3.0 interface, and backward compliant to SD 2.0 interface.

2. Product Specifications

2.1 Capacity and Device Parameters

Innodisk Industrial SD card device parameters are shown in Table 1.

Table 1: Device parameters

Capacity	User Capacity(MB)
8GB	7744
16GB	15488
32GB	30976
64GB	61952
128GB	123904

2.2 Performance

Burst Transfer Rate: up to 104 MB/s in SD 3.0 SDR104

Table 2: Performance

Capacity	8GB	16GB (128Gb*1)	16GB (64Gb*2)	32GB	64GB	128GB
Class	10	10	10	10	10	10
Sequential Read (max.)	84 MB/sec	83 MB/sec	81 MB/sec	81 MB/sec	80 MB/sec	80 MB/sec
Sequential Write (max.)	26 MB/sec	24 MB/sec	43 MB/sec	48 MB/sec	46 MB/sec	46 MB/sec

Note: Base on CrystalDiskMark 5.1.2 with file size 1000MB

2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk Industrial SD card Power Requirement

Item	Symbol	Rating	Unit
Input voltage	V _{IN}	2.7V~3.6V	V

2.3.2 Power Consumption

Table 4: Power Consumption

Mode	Power Consumption (mA)
Read	140 (max.)
Write	158 (max.)
Idle	0.2 (max.)

* Target: Industrial SD 3ME3 MLC 128GB

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for Industrial SD card

Temperature	Range
Operating	Standard Grade: -20°C to +85°C
	Industrial Grade: -40°C to +85°C
Storage	-55°C to +95°C

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for Industrial SD card

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 68-2-27

2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various Industrial SD card configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- **Failure Rate:** The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF):** A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Table 7: Industrial SD card MTBF

Product	Condition	MTBF (Hours)
Innodisk Industrial SD 3ME3	Telcordia SR-332 GB, 25°C	>3,000,000

2.5 CE and FCC Compatibility

Industrial SD card conforms to CE and FCC requirements.

2.6 RoHS Compliance

Industrial SD card is fully compliant with RoHS directive.

2.7 Reliability

Parameter	Value
Read Cycles	Unlimited Read Cycles
Flash endurance	3,000 P/E cycles
Wear-Leveling Algorithm	Support
Bad Blocks Management	Support
Error Correct Code	Support
TBW(Sequential Write)	MLC
8GB	21.8
16GB	43.6
32GB	87.2
64GB	174.5
128GB	349

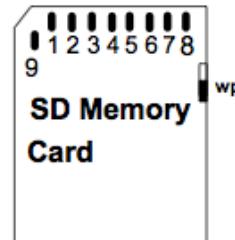
2.8 Transfer Mode

Industrial SD 3ME3 support following transfer mode:

SD 3.0 / SD 2.0

2.9 Pin Assignment

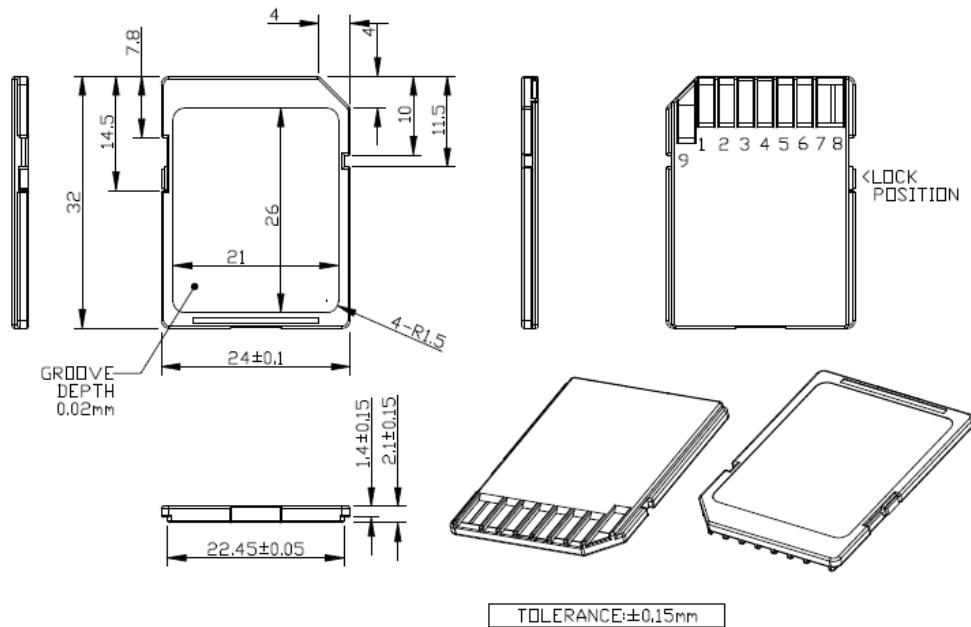
Innodisk Industrial SD 3ME3 compliant with standard SD SPEC., please refer to Table 8 for pin assignment.



Pin #	SD Mode			SPI Mode		
	Name	Type ¹	Description	Name	Type ¹	Description
1	CD/DAT3 ²	I/O/PP ³	Card Detect/Data Line [Bit 3]	CS	I ³	Chip Select (Neg. True)
2	CMD	I/O/PP	Command/Response	DI	I	Data In
3	V _{SS1}	S	Supply voltage ground	V _{SS}	S	Supply voltage ground
4	V _{DD}	S	Supply voltage	V _{DD}	S	Supply voltage
5	CLK	I	Clock	SCLK	I	Clock
6	V _{SS2}	S	Supply voltage ground	V _{SS2}	S	Supply voltage ground
7	DAT0	I/O/PP	Data Line [Bit 0]	DO	O/PP	Data Out
8	DAT1 ⁴	I/O/PP	Data Line [Bit 1]	RSV		
9	DAT2 ⁵	I/O/PP	Data Line [Bit 2]	RSV		

Table 8: Innodisk Industrial SD 3ME3 Pin Assignment

2.10 Mechanical Dimensions



2.11 Assembly Weight

An Innodisk Industrial SD card 3.0 within MLC flash ICs, 8GB's weight is 2 grams approx.

2.12 Seek Time

Innodisk Industrial SD card is not a magnetic rotating design. There is no seek or rotational latency required.

2.13 Hot Plug

The SD card support hot plug function and can be removed or plugged-in during operation.

2.14 NAND Flash Memory

Innodisk Industrial SD 3ME3 uses Multi Level Cell (MLC) NAND flash memory, which is non-volatility, high reliability and high speed memory storage.

3. Theory of Operation

3.1 Overview

Figure 2 shows the operation of Innodisk Industrial SD 3ME3 from the system level, including the major hardware blocks.

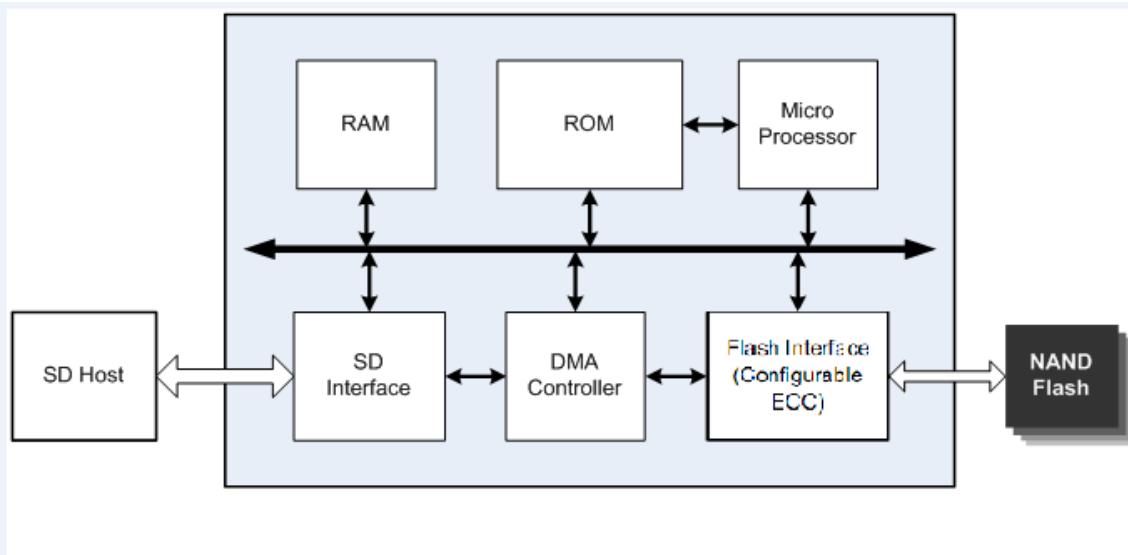


Figure 2: Innodisk Industrial SD 3ME3 Block Diagram

Innodisk Industrial SD 3ME3 integrates a SD 3.0 controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard SD interface.

3.2 SD 3.0 Controller

Innodisk Industrial SD 3ME3 is designed with a SD 3.0 controller, which has single channel for flash interface.

3.3 Error Detection and Correction

Highly sophisticated Error Correction Code algorithms are implemented. The ECC unit consists of the Parity Unit (parity-byte generation) and the Syndrome Unit (syndrome-byte computation). This unit implements an algorithm that can correct up to 43 bits per 1024 bytes in an ECC block. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without any speed penalties.

3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the **erase**

cycle limit or **write endurance limit** and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk Industrial SD 3ME3 uses a global wear-leveling algorithm to ensure that consecutive writes of a specific sector are not written physically to the same page/block in the flash. This spreads flash media usage evenly across all pages, thereby extending flash lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the product is shipped, or may develop during the life time of the SD card. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SD card implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 Garbage Collection

Garbage collection is used to maintain data consistency and perform continual data cleansing on SD card. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SD's speed and lifespan.

3.7 Power cycling

Innodisk's SD/MSDs provide the complete data protection mechanism during every abnormal power shutdown situation. Such as: power failure at programming data, updating system tables, erasing blocks, etc. The mechanism can maintain the data correctness and increase the reliability of the data stored in the NAND Flash memory.

4. Installation Requirements

4.1 Industrial SD card Pin Directions

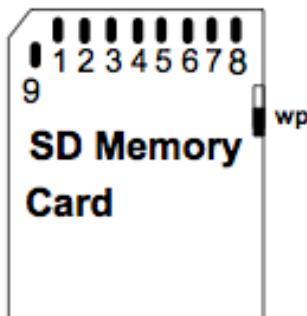


Figure 3: Signal Segment and Power Segment

4.2 Device Drive

No additional device drives are required.

5. Part Number Rule

CODE	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20											
	D	E	S	D	C	-	3	2	G	S	0	2	B	C	1	S	C	-	X	X											
Description	Disk	Industrial SD card				Capacity		Category			Flash Mode	Operation Temp.	Internal Control	CH.	Flash	-	Customized Code														
Definition																															
Code 1st (Disk)											Code 13th (Flash Mode)																				
D : Disk											B: Toshiba 15nm																				
Code 2nd ~ 5th (Form Factor)											Code 14th (Operation Temperature)																				
ESDC: Industrial SD 3ME3											C: Standard Grade (-20°C ~ +85°C)																				
Code 7th ~9th (Capacity)											W: Industrial Grade (-40°C ~ +85°C)																				
08G: 8GB											Code 15th (Internal control)																				
16G: 16GB											Code 16th (Channel of data transfer)																				
32G: 32GB											S: Single Channel																				
64G: 64GB											Code 17th (Flash Type)																				
A28: 128GB											C: Toshiba MLC																				
Code 10th ~12th (Series)											Code 19th~20th (Customized Code)																				
S02: SMI 2702BAC																															

**宣鼎國際股份有限公司
Innodisk Corporation**

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RoHS 自我宣告書(RoHS Declaration of Conformity)

Manufacturer Product: All Innodisk EM Flash and Dram products

一、 宣鼎國際股份有限公司（以下稱本公司）特此保證售予新漢股份有限公司之所有產品，皆符合歐盟 2011/65/EU 關於 RoHS 之規範要求。

Innodisk Corporation declares that all products sold to Nexcom, are complied with European Union RoHS Directive (2011/65/EU) requirement.

二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

Name of hazardous substance	Limited of RoHS ppm (mg/kg)
鉛 (Pb)	< 1000 ppm
汞 (Hg)	< 1000 ppm
鎘 (Cd)	< 100 ppm
六價鉻 (Cr 6+)	< 1000 ppm
多溴聯苯 (PBBS)	< 1000 ppm
多溴二苯醚 (PBDEs)	< 1000 ppm

立 保 證 書 人 (Guarantor)

Company name 公司名稱：Innodisk Corporation 宣鼎國際股份有限公司



Company Representative 公司代表人：Randy Chien 簡川勝



Company Representative Title 公司代表人職稱：Chairman 董事長

Date 日期：2016 / 08 / 04

宜鼎國際股份有限公司
Innodisk Corporation

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: <http://www.innodisk.com/>

REACH Declaration of Conformity

Manufacturer Product: All Innodisk EM Flash and Dram products

1. 宜鼎國際股份有限公司（以下稱本公司）特此保證此售予貴公司之產品，皆符合歐盟化學品法案(Registration , Evaluation and Authorization of Chemicals ; (EC) No 1907/2006 REACH) 以及附錄 XIV 中的限用物質之規定 (<http://www.echa.europa.eu/de/candidate-list-table> last updated: 12/01/2017 , SVHC's 173)。

所提供之產品包含：(1) 產品或產品所使用到的所有原物料；(2)包裝材料；(3)設計、生產及重工過程中所使用到的所有原物料。

We Innodisk Corporation hereby declare that our products are in compliance with the requirements according to the (EC) No 1907/2006 REACH Regulation and restricted substances in Annex XIV (<http://www.echa.europa.eu/de/candidate-list-table> last updated: 12/01/2017 , SVHC's 173).

Products include : 1) Product and raw material used by the product ; 2) Packaging material ; 3) Raw material used in the process of design, production and rework.

2. 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

InnoDisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

立 保 證 書 人 (Guarantor)

Company name 公司名稱 : InnoDisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人 : Randy Chien 簡川勝

Company Representative Title 公司代表人職稱 : Chairman 董事長

Date 日期 : 2017 / 02 / 08



DECLARATION OF CONFORMITY

This Declaration of Conformity is hereby issued to the below named company and for below described device, based on

**Technical Standard: FCC 47 CFR Part 15
Subpart B, Class B
ISED ICES-003 Issue 6, 2016**

General Information

Applicant: Innodisk Corporation
5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist.,
New Taipei City 22161, Taiwan (R.O.C)

Product Description

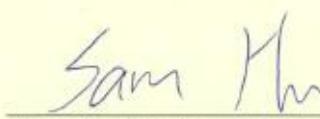
EUT Description: SD 3.0
Brand Name: Innodisk
Model Number: SD 3\$*#
\$:Flash type: (S:SLC, I:iSLC, M:MLC, T:3D TLC, A~Z:Others);
*:Product line: (E:Embedded, G:EverGreen, R:InnoRobust, S:Server, V:InnoREC, A~Z:Others);
#:Product Generation: (empty, 0~9);
SD type include (Industrial SD Card SD 3.0)

Measurement Facilities

Xindian Lab.: *Compliance Certification Services Inc.*
No. 163-1, Jhongsheng Rd., Xindian Dist., New Taipei City, 23151 Taiwan.
Tel: +886-2-22170894 / Fax: +886-2-22171029

This device has been tested and found to be in compliance with the measurement procedures specified in the Standards & Specifications listed above and as indicated in the measurement report with the number: TI70707D04-D

The test results shown in this report are applicable only to the investigated sample identified in this report.



Sam Hu / Assistant Manager
Date: July 12, 2017



VERIFICATION OF COMPLIANCE

This Verification of Compliance is hereby issued to the below named company and for below described product, based on

**Technical Standard: EMC DIRECTIVE 2014/30/EU
(EN55032 / EN55024)**

General Information

Applicant: Innodisk Corporation
5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist.,
New Taipei City 22161, Taiwan (R.O.C)

Product Description

EUT Description: SD 3.0
Brand Name: Innodisk
Model Number: SD 3\$*#
\$:Flash type: (S:SLC, I:iSLC, M:MLC, T:3D TLC, A~Z:Others);
*:Product line: (E:Embedded, G:EverGreen, R:InnoRobust, S:Server, V:InnoREC, A~Z:Others);
#:Product Generation: (empty, 0~9);
SD type include (Industrial SD Card SD 3.0)

Measurement Standard

EN 55032: 2015 / AC: 2016
CISPR 32: 2015 (Ed 2.0) / CI: 2016
EN 61000-3-2: 2014
EN 61000-3-3: 2013
EN 55024: 2010 + A1: 2015
(IEC 61000-4-2: 2008; IEC 61000-4-3: 2006 + A1: 2007 + A2: 2010; IEC 61000-4-4: 2012;
IEC 61000-4-5: 2014; IEC 61000-4-6: 2013; IEC 61000-4-8: 2009; IEC 61000-4-11: 2004)

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Tel: +886-2-22170894 / Fax: +886-2-22171029

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Sam Hu / Assistant Manager
Date: July 12, 2017